



中国科学院高能物理研究所
Institute of High Energy Physics
Chinese Academy of Sciences



Science & Technology
Facilities Council



NATIONAL
ACCELERATOR
LABORATORY

CMOS Strip Sensor Characterization for the ATLAS Phase-II Strip Tracker Upgrade

Liejian Chen (IHEP)

On behalf of IHEP ATLAS Group

Many thanks for ATLAS CMOS Strip Calibration

Yubo Han¹, Hongbo Zhu¹, Giulio Villani², Iain Sedgwick², Jens Dopke², Zhige Zhang², Steve MacMahon², Fergus Wilson², Dionisio Doering³, Pietro Caragiulo³, Larry Ruckman³, Camillo Tamma³, Mazin Khader³, Murtaza Safdari³, Su Dong³

¹ Institute of High Energy Physics, Beijing, China

² Rutherford Appleton Laboratory, Didcot, UK

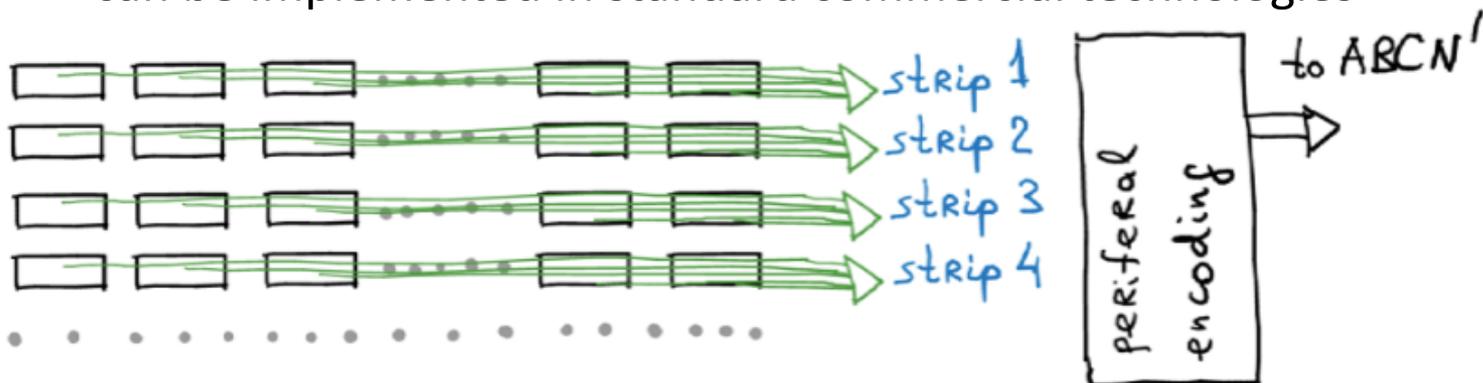
³ SLAC National Accelerator Laboratory, CA, USA

Outline

- **Introduction of CMOS Strip**
- **Primary test results of OverMOS**
- **Test results of the Chess 2 in-pixel electronics**
- **Conclusion**

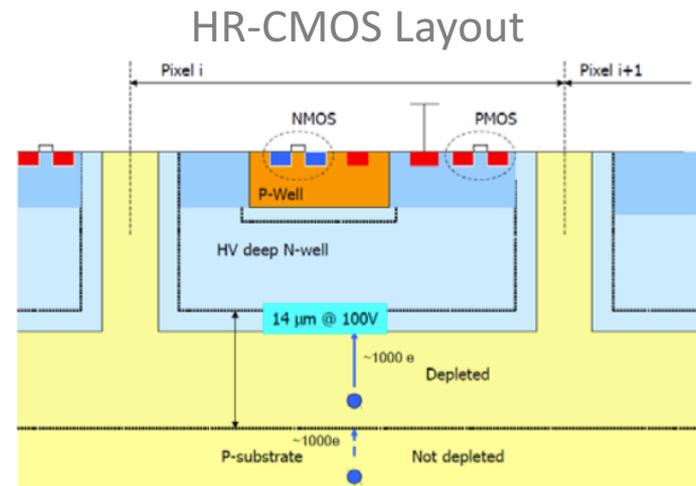
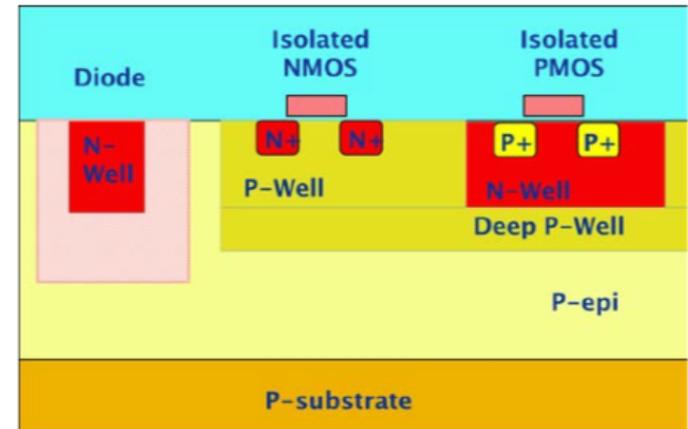
CMOS Strips Introduction

- ATLAS evaluate HV/HR CMOS technologies for strip region
 - “Strip” is composed from pixels with individual readout
 - Similar readout chain: sensor (Analog FE + comparators)->ABCN’->HCC’
- Possible improvements compared to present strip sensor:
 - **Significantly lower material budget**
 - eliminate the need for bump bonding or other challenging interconnect methods
 - can be thinned to less than 100um
 - **Smaller pixel size**
 - not limited by bump bonding
 - **Lower costs**
 - can be implemented in standard commercial technologies



HV/HR-CMOS Technology

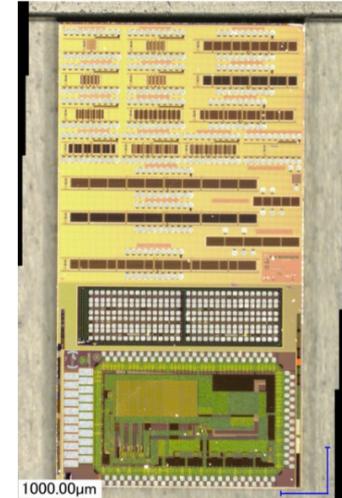
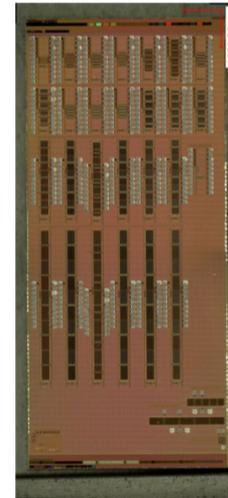
- Depleted CMOS benefits from HV/HR technology
 - $Q_{MIP} \propto d \propto \sqrt{\rho \times V}$
- High-Resistivity CMOS technology
 - Developed for image applications
 - Depletion zone $\sim 10\text{-}20\mu\text{m}$
 - High resistivity: up to $\text{k}\Omega\cdot\text{cm}$
 - TowerJazz-OverMOS 1 -> TowerJazz OverMOS 1.1
- High-Voltage CMOS technology
 - Standard n-in-p sensor
 - Depletion zone $\sim 10\text{-}20\mu\text{m}$
 - High bias voltage: $\sim 100\text{ V}$
 - Challenging for hybrid pixel readout electronics
 - AMS-Chess1 -> AMS-Chess2



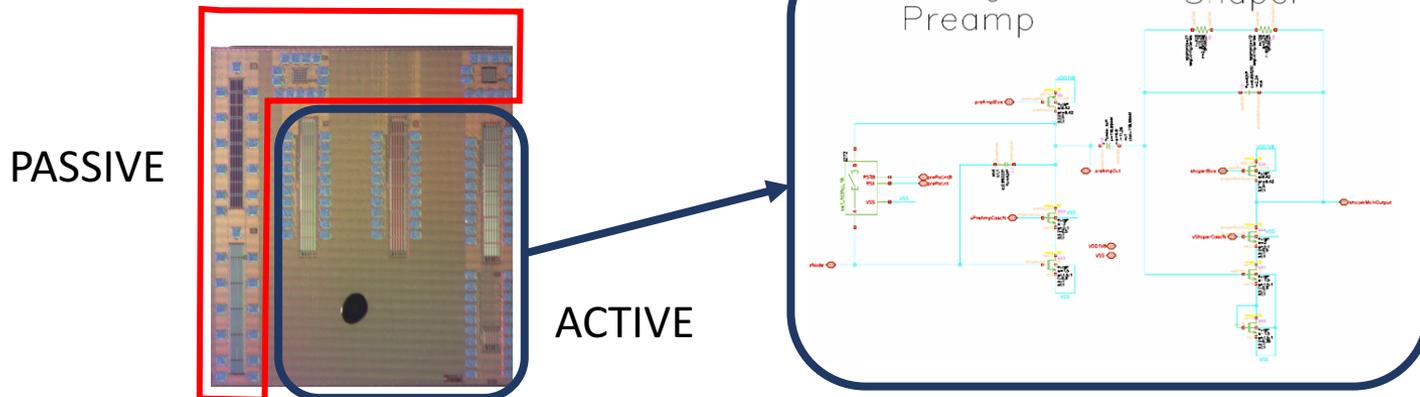
HV-CMOS Layout

Introduction of OverMOS

- OverMOS 1.0
 - P and n type substrates
 - Numbers of topology of the collecting n-wells
 - **But it has shortage problems**
- OverMOS 1.1
 - similar structure, but collection n-wells surrounded with P-type rings
 - Passive pixel arrays (40X40um², 40X400 um²)
 - Active pixel arrays: **AC/DC** coupled with In-pixel electronics (40 X 400 um²)

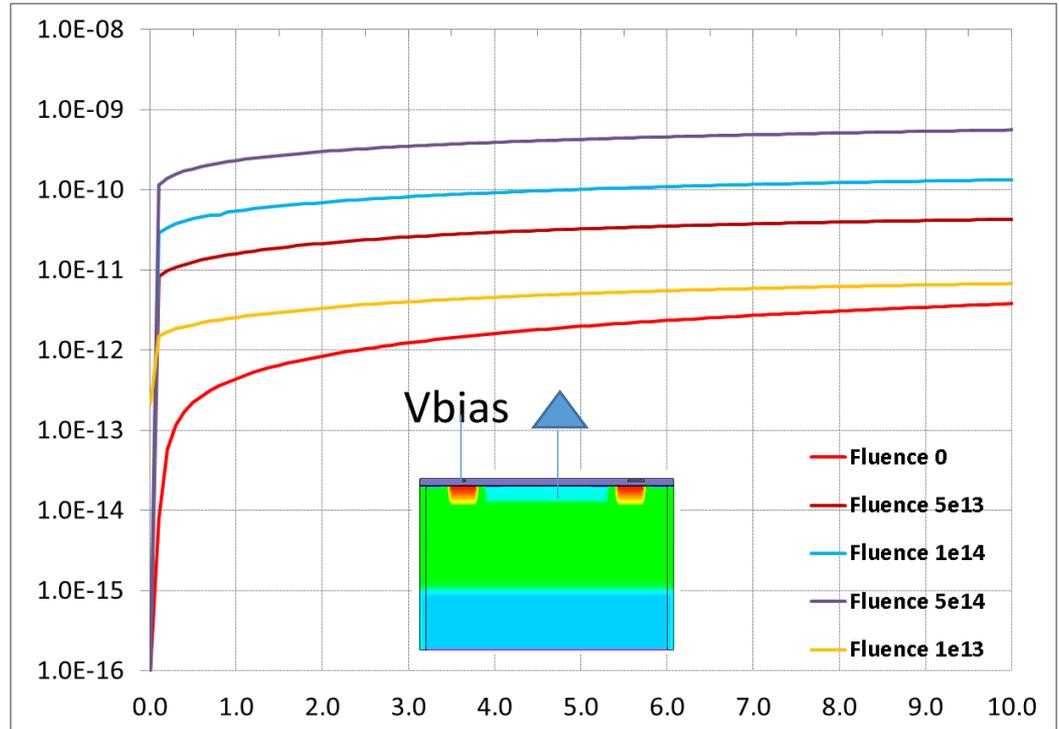
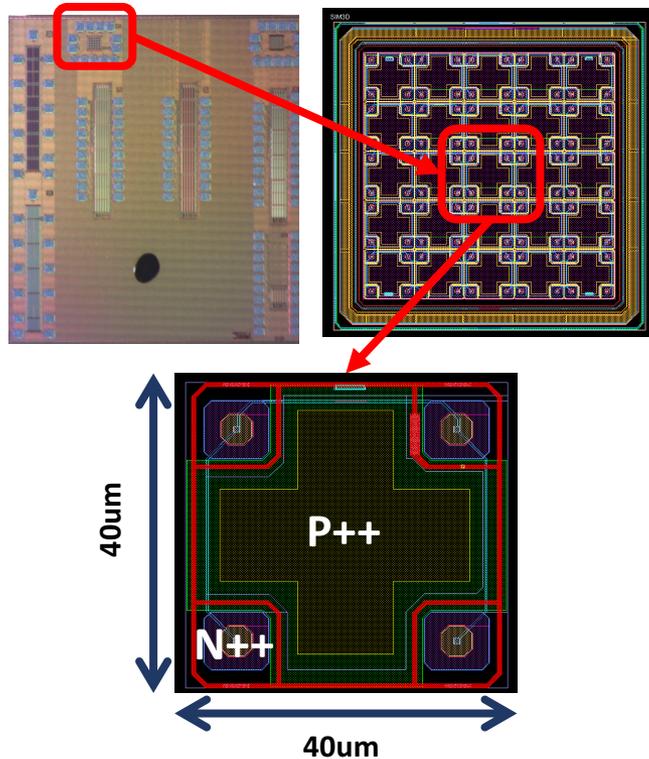


OverMOS 1 with p/n type sub



OverMOS 1.1 with p type sub

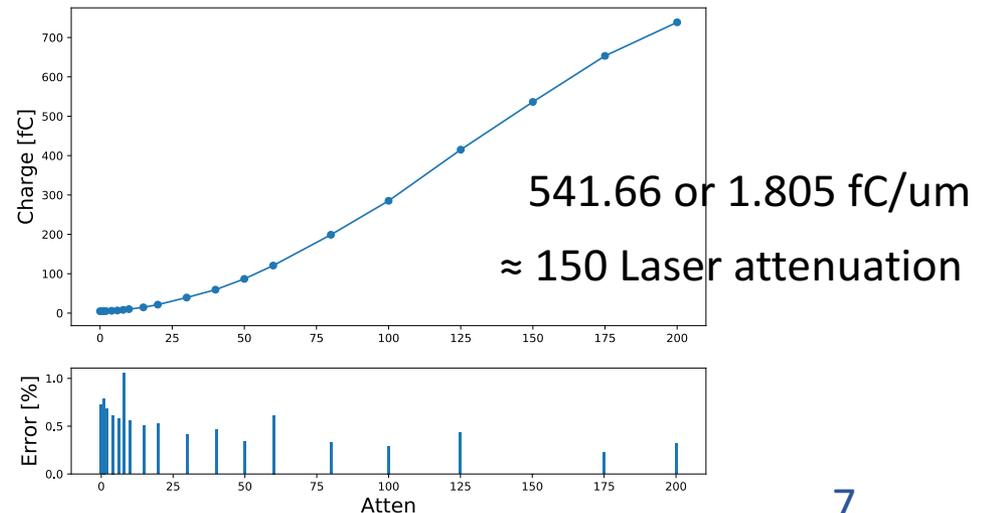
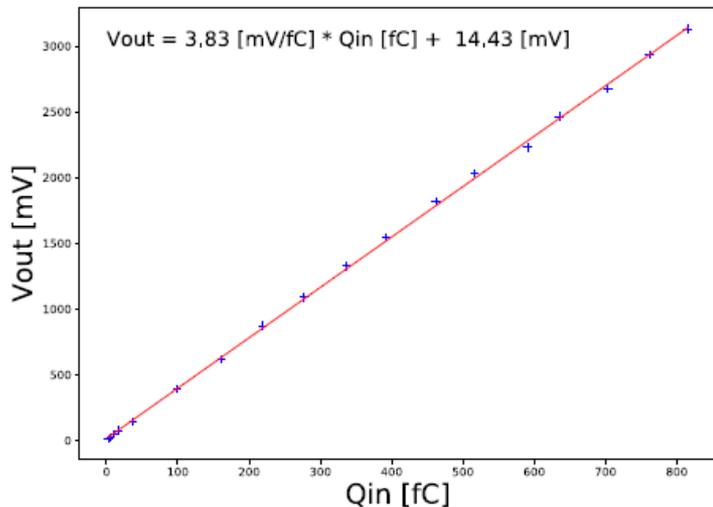
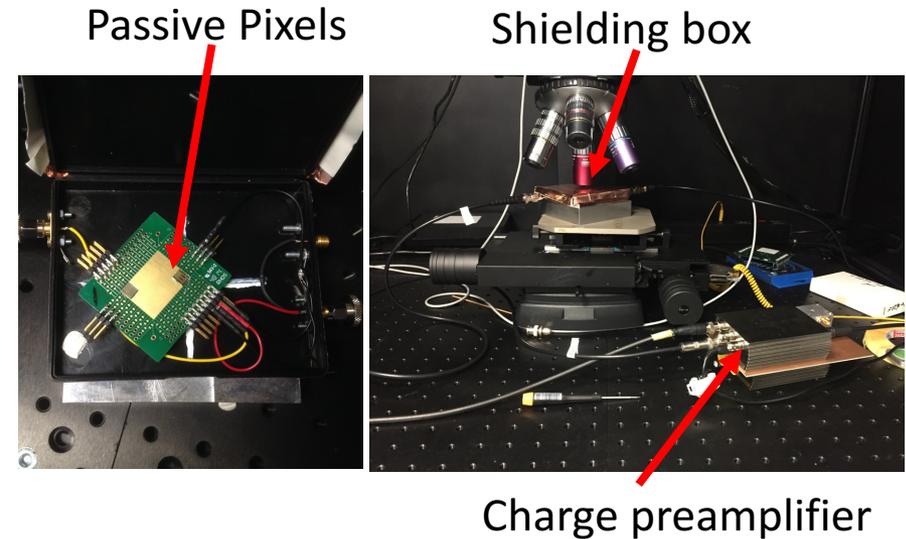
Passive Pixel DC Properties



- Probing the central pixel (40X40 μm²): HV bias voltage applied to n-well and p-well grounded
- Irradiated at Ljubljana in October 2017: 1e13, 5e13, 1e14 and 5e14 n_{eq}/cm²

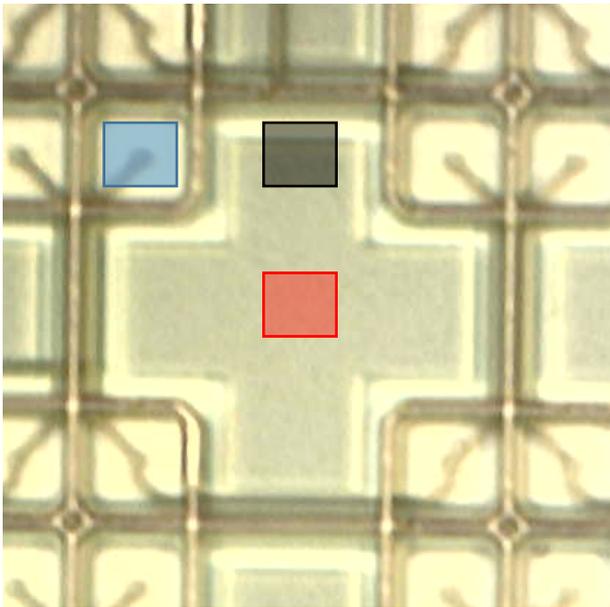
Laser Injection on Passive Pixels

- Signal of the sensor amplified with an external preamplifier (A250CF coolFET Charge preamplifier)
- Bias voltage applied through the port of A250CF
- Laser information:
 - ND filter: 1.3 + 3 (decrease intensity)
 - Lo_IR (1064 nm)
 - Shutter: 4.5x4.5 μm^2

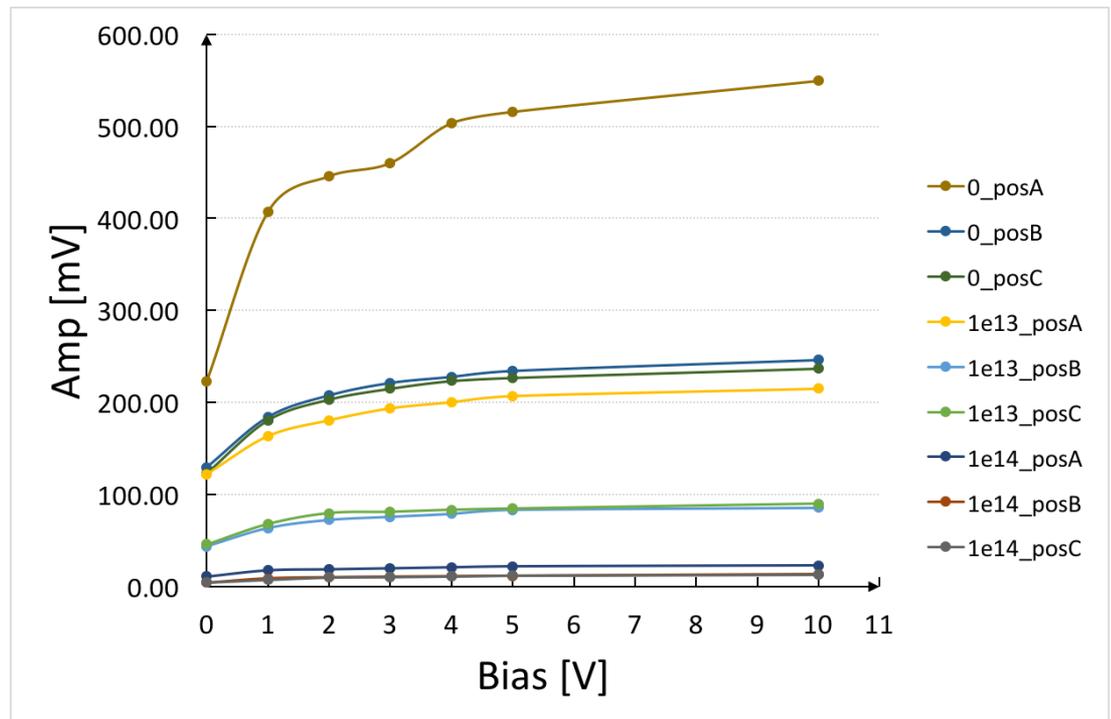


Laser Response of Passive Pixels

- Total collected charge vs. V_{bias} , points A,B,C. Integration time 400 ns
- $\langle Q \text{ injected} \rangle = 1.805 \text{ fC}/\mu\text{m}$
- HVbias provided through the A250CF, via a 400 Meg resistor chain

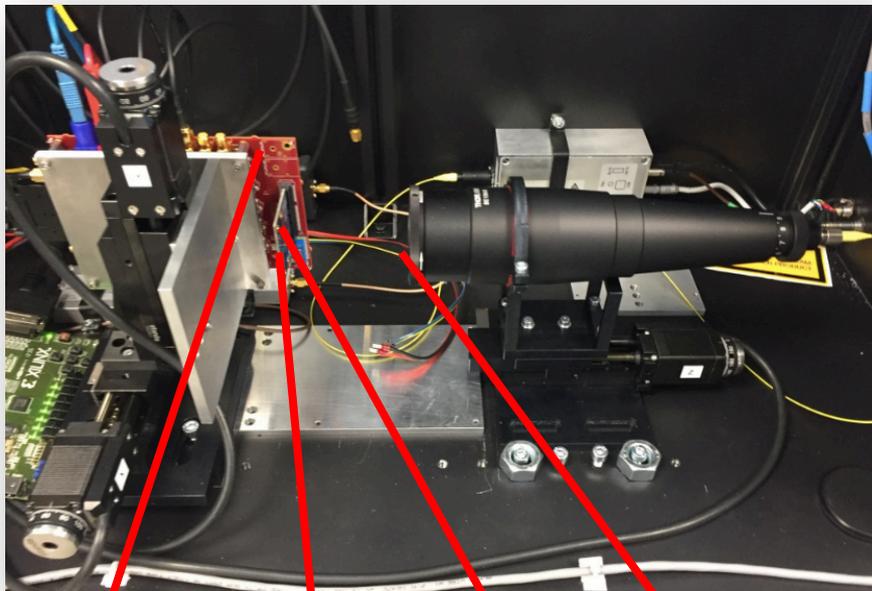


Pos A: Blue	(0,0)
Pos B: Black	(15,0)
Pos C: Red	(15,-15)



TCT Measurements on Active Pixel Arrays

- TCT scanning on active pixel arrays confirm that the shortage problem have been solved
- The diodes are isolated by P-rings in OverMOS 1.1, so only the hit channel does show a significant response with negligible crosstalk comparing to OverMOS1.0

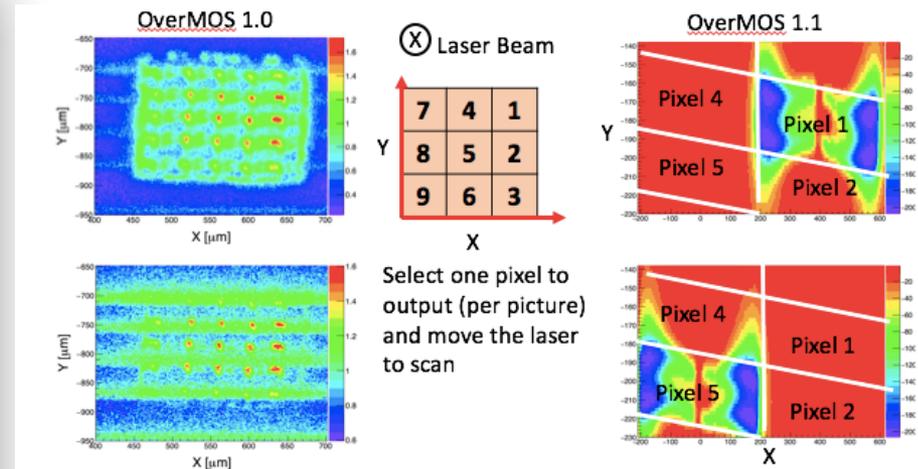


Mather
board

Daughter
board

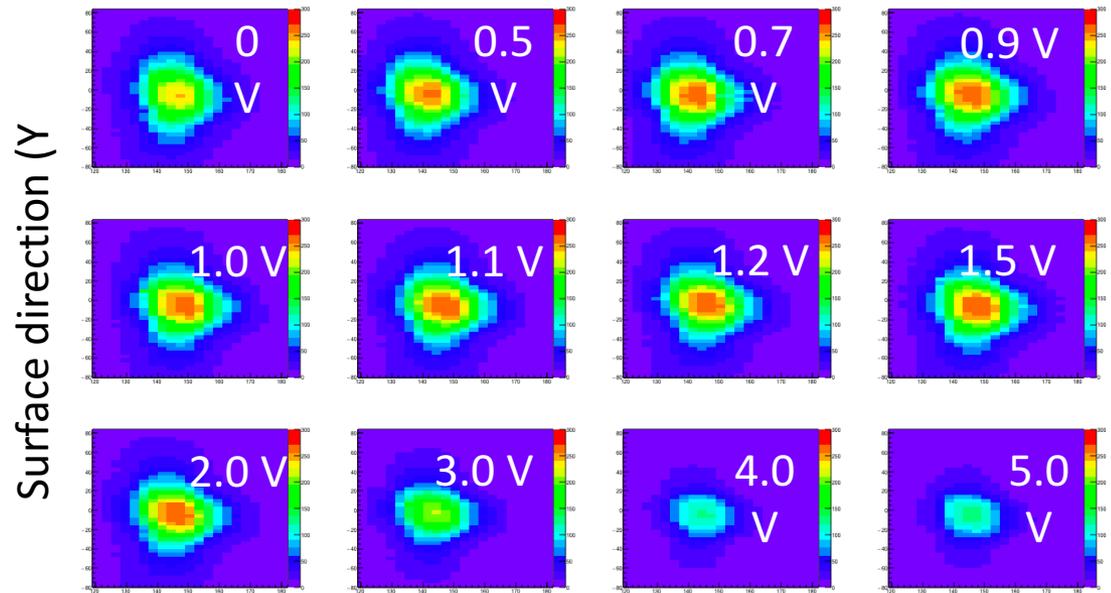
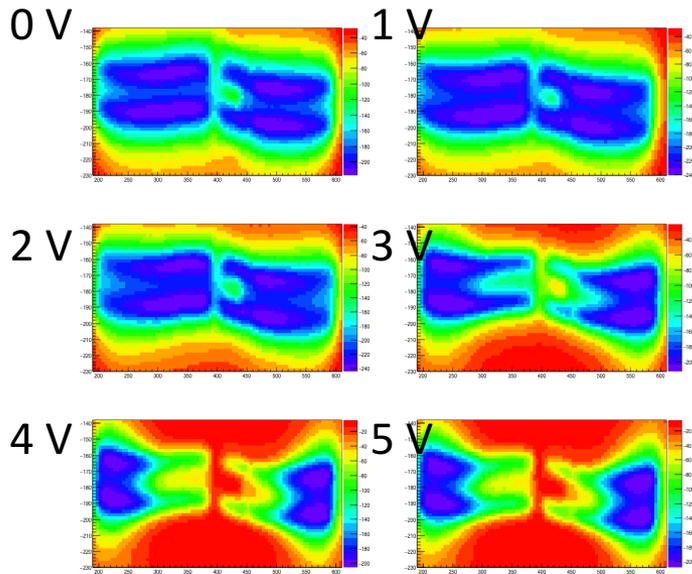
Sensor

Laser



Top-TCT/Edge-TCT

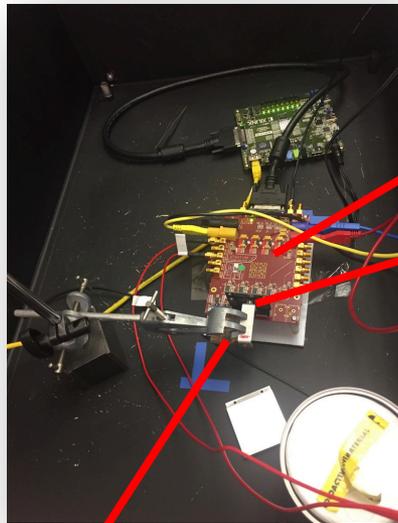
- Top-TCT and Edge-TCT scanned indicate the bias strange behavior



Depth direction (X [um])

^{55}Fe Experiment

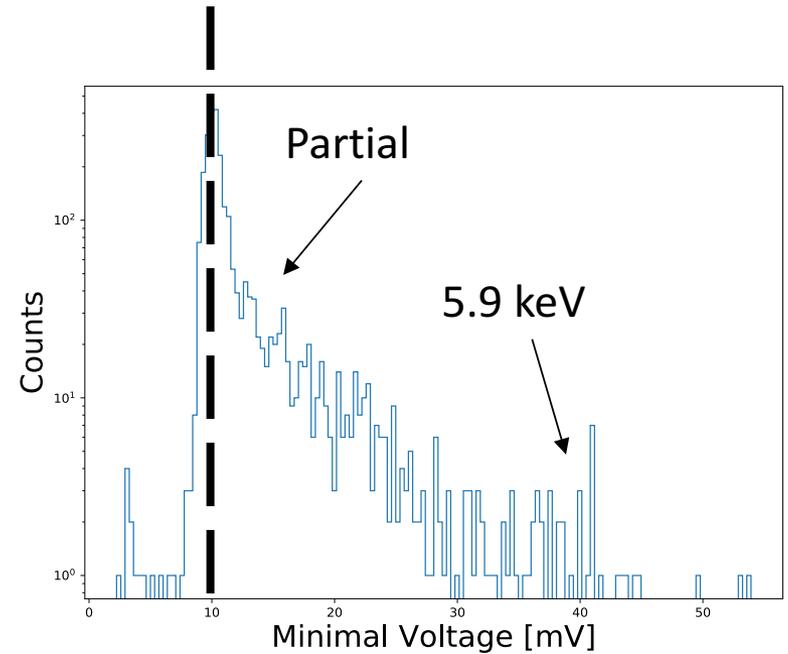
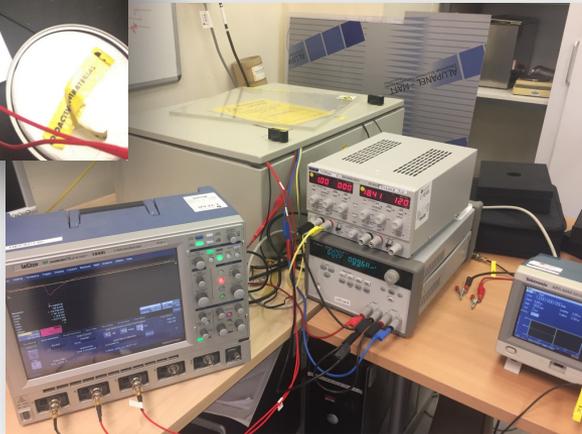
- ^{55}Fe 5.9 keV/3.6 eV \approx 1640 e^-
- Not very clear spectrum due to low statistic



Mather board

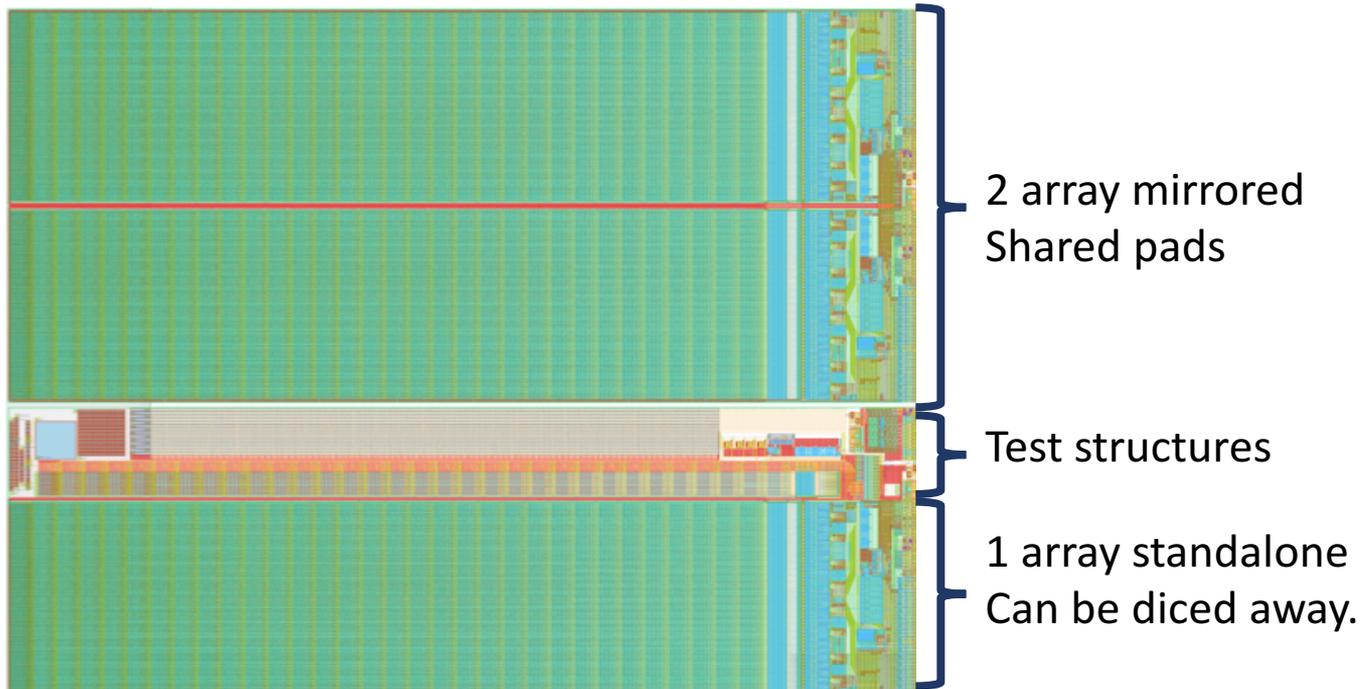
Sensor bonded on daughter board

^{55}Fe source



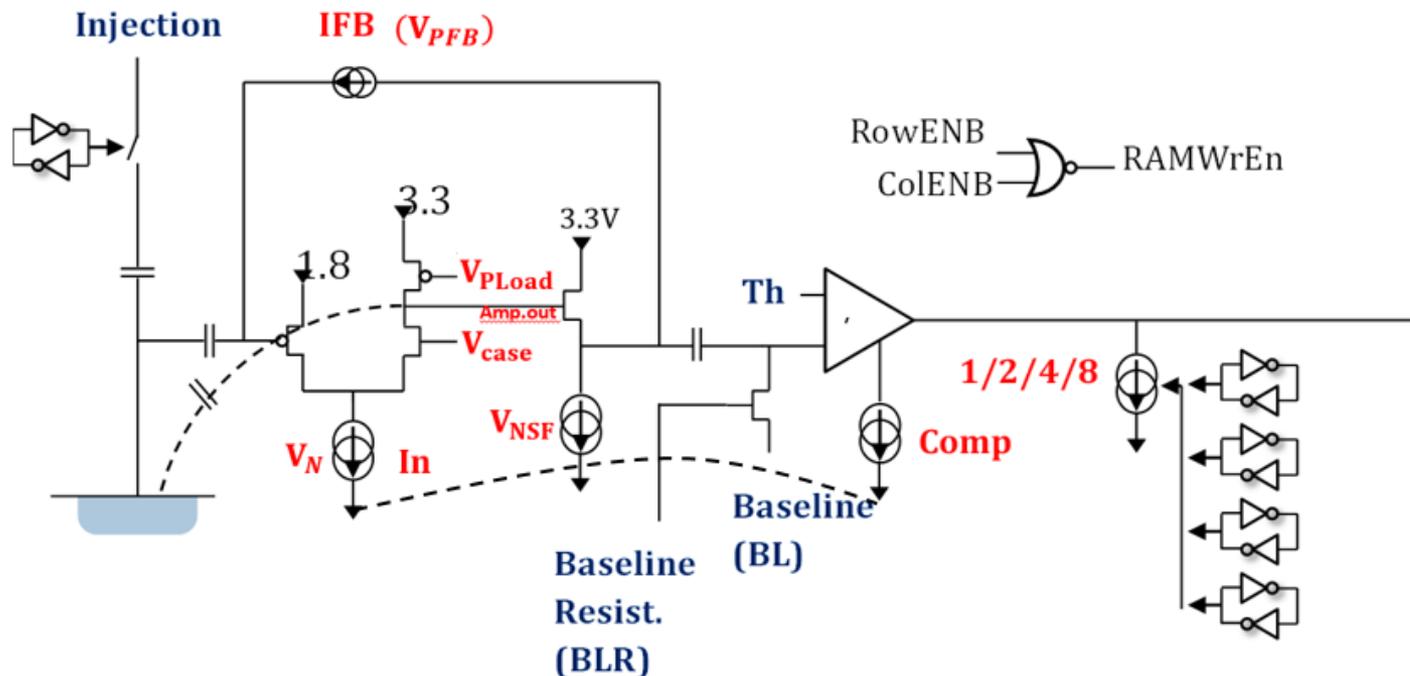
Introduction of AMS-Chess2

- Designed at UCSC and SLAC, manufactured in the AMS-H35 technology by AMS after being successful in prototypes HV-CMOS Chess1
- n-in-p with 4 substrate resistivities (20 – 1000 $\Omega\cdot\text{cm}$)
- Full reticle monolithic demonstrator chip
- 3 fully digital striplet arrays + 1 test filed with analog test structures
- IHEP (Yubo) attend the test of in-pixel electronics



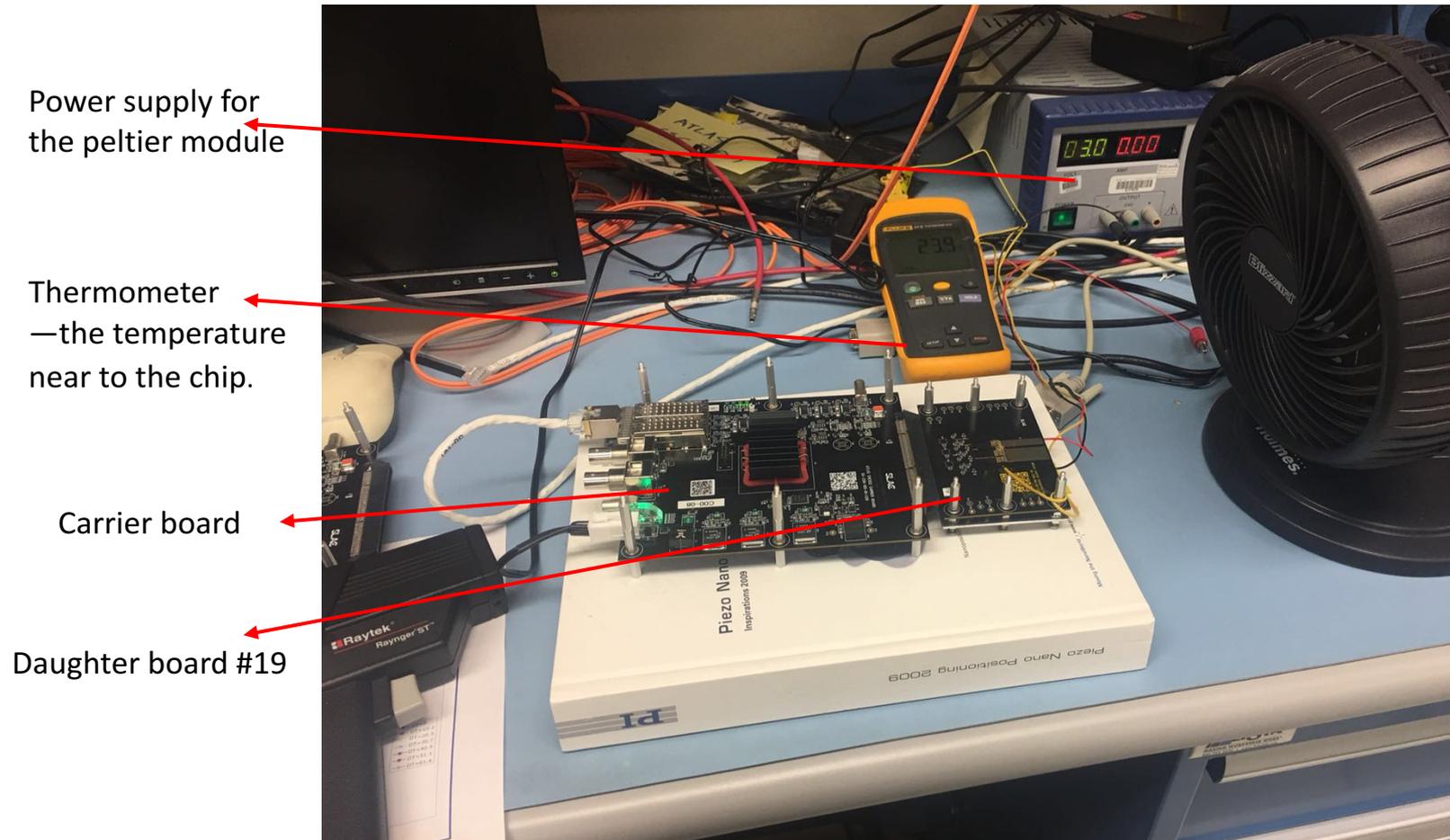
In-pixel Electronics

- Charge preamplifier and comparator are implanted in pixels
- Challenging in adjustment to make the electronics work stable



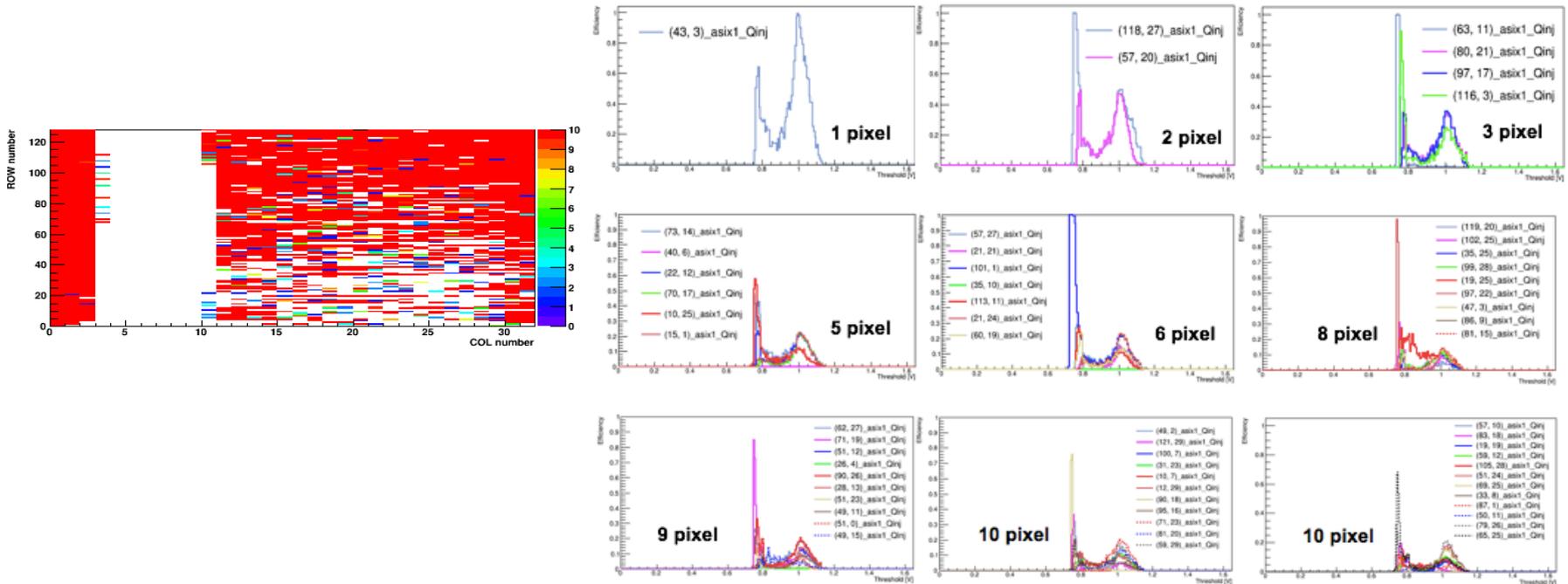
Test on ASICs

- Cooling module added to reduce the noise
- Acquire stable results with good BL/threshold linearity
- Update firmware to enable external pulse injection



Test Results of Chess2

- Average efficiency of multiple pixels @ different external pulses injected
- Beam test is on gonging after enable bias the board



Conclusion

- ATLAS commenced R&D effort to evaluate depleted CMOS pixels (HV/HR)
- IHEP attend most test of OverMOS 1.1 and Chess 2 in-pixel electronics test
- Better understanding of HR-CMOS sensor before/after irradiation and HV-CMOS in-pixel electronics